Final Product Change Notification | 201903007F01

Issue Date: 30-Mar-2019
Effective Date: 28-Jun-2019

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

This notice is NXP Company Proprietary.

Management Summary

BE2 tranferring from ASEK to ATKH (grinding/sawing/marking and packing).
BE2 (back half of the Assembly process) will be enabled in ATKH.

Change Category

[ ] Wafer Fab Process	[ ] Assembly Process	[ ] Product Marking	[ ] Test Location	[ ] Design
[ ] Wafer Fab Materials	[ ] Assembly Materials	[ ] Mechanical Specification	[ ]Test Process	[ ] Errata
[ ] Wafer Fab Location	[ ] Assembly Location	[ ] Packing/Shipping/Labeling	[ ] Test Equipment	[ ] Electrical spec./Test coverage
[ ] Firmware	[X] Other - BE2 process transferring (Grinding/Sawing/Marking/Packing)			

ASEK Grinding/Sawing Transferring to ATKH - PCA9412AUK

Description of Change

Expanding the current flow which is currently limited to an ASE Assembly to allow for ATKH BE2.
The flow allows for manufacturing flexibility and helps ensure customer supply.
BE2(back half of the Assembly process) (grinding/sawing/marking and packing) will be enabled in ATKH.
There's no change in Form, Fit or Function.

Reason for Change

Expanding the current flow which is currently limited to an ASE Assembly to allow for ATKH BE2.
The flow allows for manufacturing flexibility and helps ensure customer supply.

Identification of Affected Products

Product identification does not change
Expanding the current flow which is currently limited to an ASE Assembly to allow for ATKH BE2.
The flow allows for manufacturing flexibility and helps ensure customer supply.

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 30-Apr-2019

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 29-Apr-2019.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

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